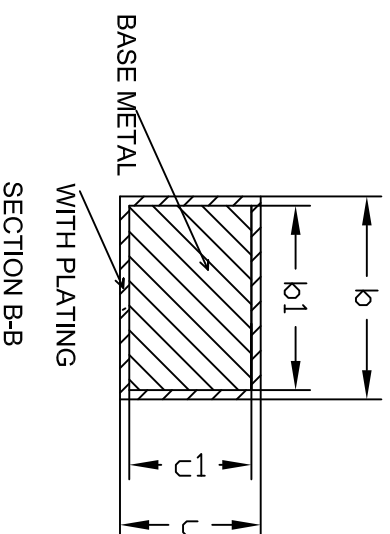
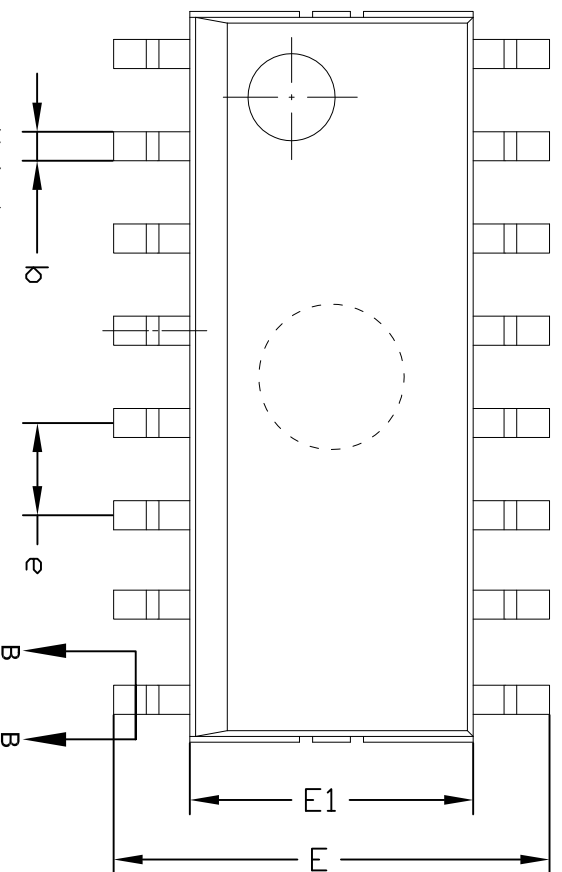
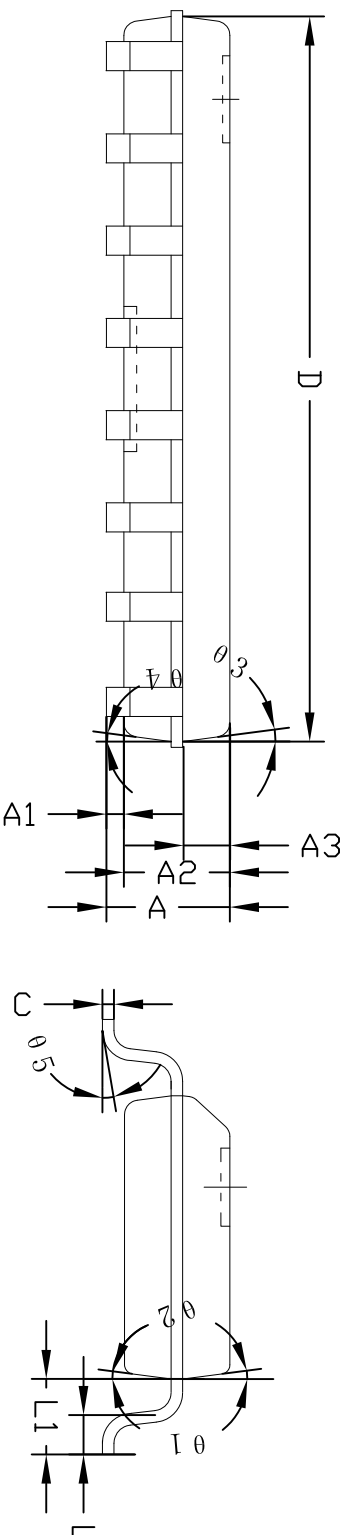




SOP16 PACKAGE OUTLINE DIMENSIONS



- 技术说明:
- 1) LEADFRAME MATERIAL: COPPER;
引线框架材料: 铜;
 - 2) LEADFRAME THICKNESS: 0.203mm;
引线框架厚度: 0.203mm;
 - 3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;
塑封体长度及宽度尺寸不包括塑封溢胶;
 - 4) REFERENCE: JEDEC MS-013, MS-012。
参考标准: JEDEC MS-013, MS-012。

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.70
A1	0.10	0.15	0.21
A2	1.40	1.45	1.50
A3	0.60	0.65	0.70
b	0.39	--	0.46
b1	0.38	0.41	0.44
c	0.20	--	0.24
c1	0.19	0.20	0.21
D	9.50	9.90	10.05
E	5.80	6.00	6.20
E1	3.75	3.85	4.00
e	1.27(BSC)		
L	0.50	0.60	0.70
L1	1.10(REF)		
theta1	6°	~	11°
theta2	6°	~	11°
theta3	5°	~	10°
theta4	6°	~	10°
theta5	0°	~	6°